

a² This application is a divisional application under 37 C.F.R. §1.53(b) of prior application Serial No. 09/254,119 filed April 16, 1999 which is a 35 U.S.C. 371 of PCT/JP97/02987 filed August 27, 1997. The disclosures of the specification, claims, drawings and abstract of application Serial No. 09/254,119 and PCT/JP97/02987 are incorporated herein by reference.

In The Title

Cancel the current title of the invention and replace it with the following new title:

a³ →PROCESS FOR PRODUCING SEMICONDUCTOR DEVICE
PROVIDED WITH LOW MELTING POINT METAL BUMPS.

REMARKS

Entry of this Preliminary Amendment prior to calculating the filing fee is respectfully requested. The present application is a 37 C.F.R. §1.53(b) divisional application of prior application Serial No. 09/254,119.

The present application is directed to process

claims which were withdrawn from consideration in prior application Serial No. 09/254,119. Product claims 1-6, under consideration in prior application Serial No. 09/254,119, have been canceled by the present amendment.

Claims 9, 13, 14 and 15 have been amended to eliminate multiple dependent claims in order to reduce the filing fee.

The specification has been amended to recite
continuing information.

The title of the invention has been amended to
reflect the subject matter under consideration in the claims
of the present application.

New matter is not being presented by the present
amendment.

An action on the merits is respectfully requested.

Respectfully submitted,

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